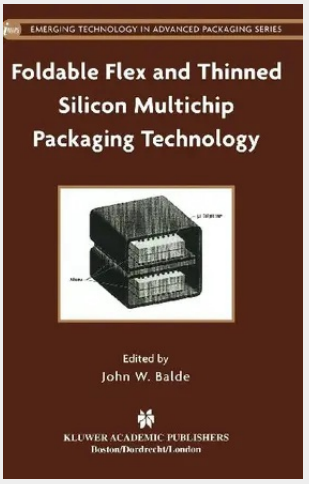
Balde

Foldable Flex and Thinned Silicon Multichip Packaging Technology

Foldable Flex and Thinned Silicon Multichip Packaging Technology presents newly emerging methods used to make stacked chip packages in the so-called 2-1/2 D technology (3-D in physical format, but interconnected only through the circuits on folded flex). It is also being used in single chip packages where the thinness of the chips and the flex substrate made packages significantly thinner than through any other means.

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